

07-03-01

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JC962 U.S. PTO
06/26/01



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: George Hsieh

Title: USING THE WAVE SOLDERING PROCESS TO ATTACH MOTHERBOARD CHIPSET HEAT SINKS

Attorney Docket No.: 884.462US1

PATENT APPLICATION TRANSMITTAL

BOX PATENT APPLICATION

Commissioner for Patents
Washington, D.C. 20231

We are transmitting herewith the following attached items and information (as indicated with an "X"):

- Return postcard.
- Utility Patent Application under 37 CFR § 1.53(b) comprising:
 - Specification (15 pgs, including claims numbered 1 through 30 and a 1 page Abstract).
 - Formal Drawing(s) (7 sheets).
- Signed Combined Declaration and Power of Attorney (3 pgs).
- Check in the amount of \$890.00 to pay the filing fee.
- Assignment of the invention to Intel Corporation (2 pgs) and Recordation Form Cover Sheet.
- Check in the amount of \$40.00 to pay the Assignment recording fee.

The filing fee has been calculated below as follows:

	No. Filed	No. Extra	Rate	Fee
TOTAL CLAIMS	30 - 20 =	10	x 18 =	\$180.00
INDEPENDENT CLAIMS	3 - 3 =	0	x 80 =	\$0.00
[] MULTIPLE DEPENDENT CLAIMS PRESENTED				\$0.00
BASIC FEE				\$710.00
				\$890.00
TOTAL				

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